

Theme-based objectives and endpoints



Objective: Design and create increasingly high-performance power converters and supply devices targeting :
 Compactness - Performance - Compatibility with the environment

Through decisive actions involving :

- New semiconductor devices (GaN, diamond, SiC) : gate driver and characterization
- Power integration : packaging concepts, EMI, cooling...
- Converter design : topologies, modular converters, system level converters networks...
- Innovative design methods and tools : electroMagnetic modeling, optimization-oriented models

Keywords : modelling, integrated power electronics, EMC, gate drivers, packaging, power converters design and optimization, cooling.



Scientific activities

Power devices and integration

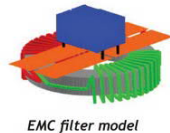
- Semiconductor devices
- 2D and 3D integration including wafer level packaging,
 - Gate drivers,
 - Thermal and electrical characterization
- Passive devices
- Integration,
 - Characterization
- Converter integration
- Integrated modular converter from elementary cells

Power converter Design

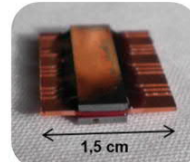
- Topologies, control, design
- Targets
- Multisource converters,
 - Modular converters,
 - Applications with high constraints

Modelling, methodologies and design tools

- Devices and EMC modelling
- Converters, Systems (network, plane...),
 - Evolution of standards (PLC, EMC, ...),
 - Semiconductor devices,
 - Passive devices
- Methodologies for converter design
- Tools for rapid prototyping



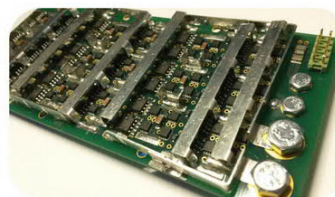
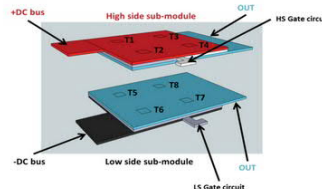
Achievements



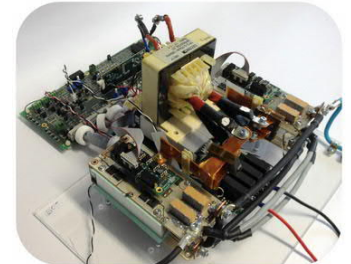
Wafer level packaging (CEA/LETI)



DC-DC converter (15V-5W) with insulation voltage capabilities up to 40kV (Schneider)



DC/DC converter from elementary conversion cells



4kW DC-DC Triple Active Bridge Converter for Aircraft Application (Thales)

Experimental facilities

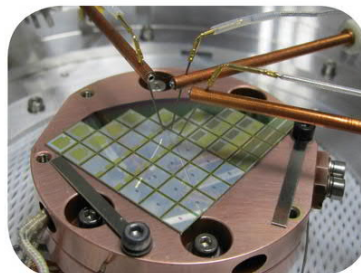
Semiconductor Characterization

Electrical characterization (Temp. 77K-675K)
 Thermal impedance measurement.

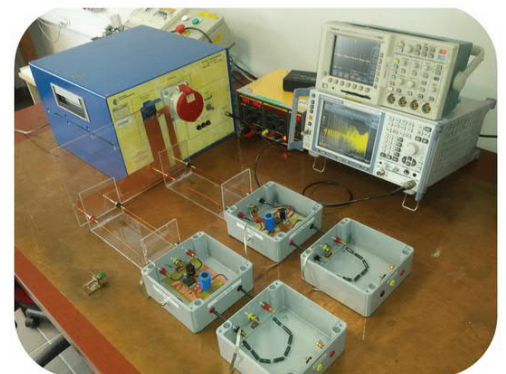
EMC test bench

Technology platforms

CIME Nanotech Clean Rooms and packaging facilities acces



Component testing facility CARAPACE



EMC test of a converter network

Collaborative projects

Industrial projects

Alstom, Altair, Eaton, Ecoways, Freemens, Hager, Luxol, Microspire, Mitsubishi, Renault Truck, Schneider-Electric, Siemens, Thalès, ST Microelectronics, Safran

European project

Green-diamond

Start-up

Freemens (Battery Management Systems)
 Sirepe (Power converters design)

National Projects

National research agency, OSEO, FUI, Région Rhone-Alpes, Institut Carnot Energies du Futur, Laboratoires d'Excellence: LANEF, GaNEX, IEED Supergrid

Academic partners

Research group with CEA/LETI, and SAFRAN
 Others in Grenoble: CIME Nanotech/PTA, LEGI, Néel Institute, IMEP, SIMAP...
 National : Ampère (Lyon), LAPLACE and LAAS (Toulouse), SATIE and IFST-TAR (Paris), INES (Le Bourget du Lac).
 International: Algérie, Allemagne, Brésil, Bulgarie, Canada, GB, Iran, Japon, Mexique , Pérou, USA

